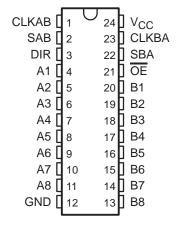
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

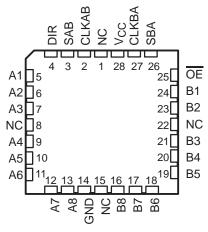
These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT646.

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both.

SN54ABT646 . . . JT PACKAGE SN74ABT646 . . . DB, DW, NT, OR PW PACKAGE (TOP VIEW)



SN54ABT646 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus will receive data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT646 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT646 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT646 is characterized for operation from -40° C to 85° C.

EPIC-IIB is a trademark of Texas Instruments Incorporated



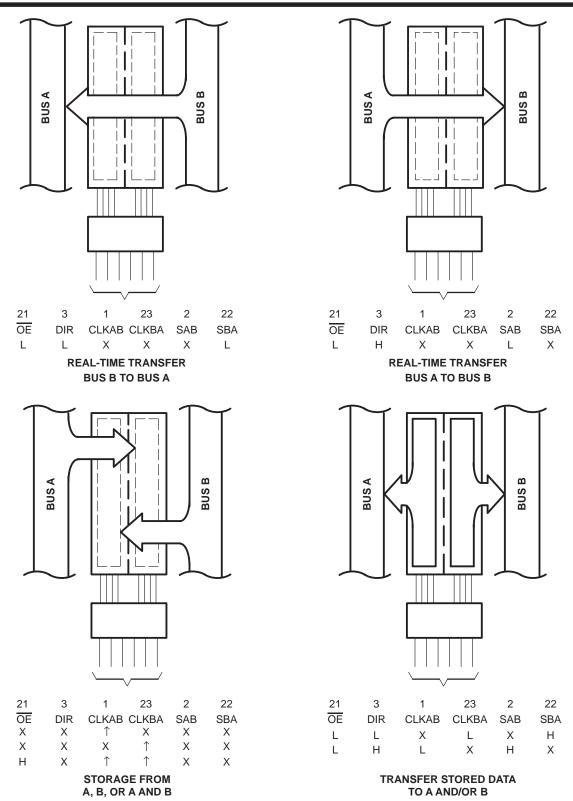


Figure 1. Bus-Management Functions

Pin numbers shown are for DB, DW, JT, NT, and PW packages.

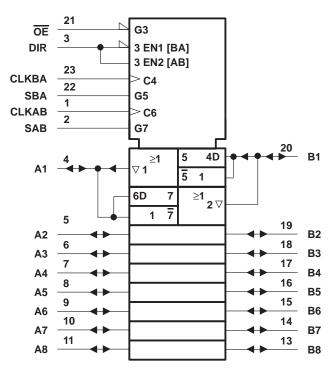


FUNCTION TABLE

INPUTS						DATA	A I/Os	OPERATION OR FUNCTION		
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OPERATION OR FUNCTION		
Х	Х	1	Χ	Χ	Χ	Input	Unspecified [†]	Store A, B unspecified [†]		
Х	Χ	Χ	\uparrow	Χ	Χ	Unspecified [†]	Input	Store B, A unspecified [†]		
Н	Х	1	↑	Х	Χ	Input	Input	Store A and B data		
Н	Χ	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage		
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus		
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus		
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus		
L	Н	H or L	Χ	Н	X	Input	Output	Stored A data to B bus		

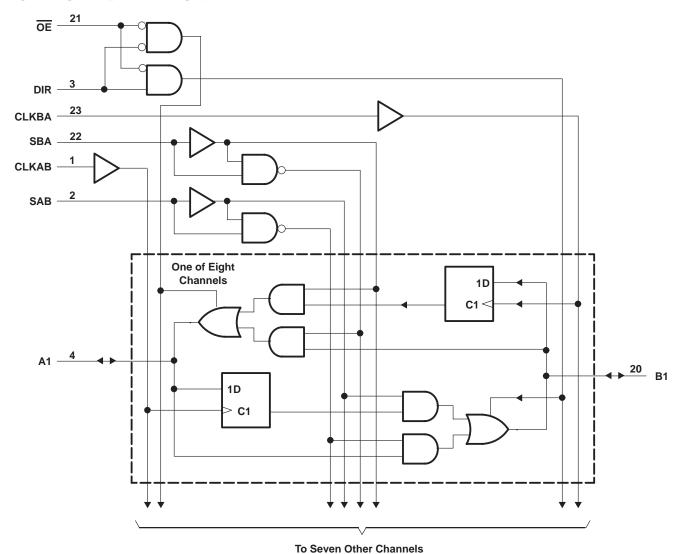
[†] The data output functions may be enabled or disabled by various signals at the $\overline{\text{OE}}$ and DIR inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every low-to-high transition of the clock inputs.

logic symbol‡



[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V _O	. −0.5 V to 5.5 V
Current into any output in the low state, I _O : SN54ABT646	96 mA
SN74ABT646	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	−50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 2): DB package	0.65 W
DW package	1.7 W
NT package	1.3 W
PW package	0.7 W
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

 The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54A	BT646	SN74A	UNIT	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EN	2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0 <	Vcc	0	VCC	V
loh	High-level output current	40,	-24		-32	mA
IOL	Low-level output current	700	48		64	mA
Δt/Δν	Input transition rise or fall rate) V	5		5	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

SN54ABT646, SN74ABT646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS068E - JULY 1991 - REVISED JULY 1994

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS			Т	A = 25°C	;	SN54A	BT646	SN74A	BT646	UNIT
PARAMETER				MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII
VIK	V _{CC} = 4.5 V,	I _I = -18 mA				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5		
\/	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$		3			3		3		v
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$		2			2				V
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$		2*					2		
Voi	V00 - 45 V	I _{OL} = 48 mA				0.55		0.55			V
VOL	V _{CC} = 4.5 V	I _{OL} = 64 mA				0.55*		4		0.55	
II	V _{CC} = 5.5 V,		Control inputs			±1		±1		±1	μΑ
''	$V_I = V_{CC}$ or GND		A or B ports			±100		±100		±100	μΑ
lozh [‡]	$V_{CC} = 5.5 V$,	V _O = 2.7 V				10§	1	50		10§	μΑ
I _{OZL} ‡	$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V				-10§	2	-50		-10§	μΑ
l _{off}	$V_{CC} = 0$,	V_I or $V_O \le 4.5$	/			±100	20			±100	μΑ
ICEX	$V_{CC} = 5.5 V,$	V _O = 5.5 V	Outputs high			50	Q	50		50	μΑ
ΙΟ¶	$V_{CC} = 5.5 V,$	$V_0 = 2.5 \text{ V}$		-50	-100	-180	-50	-180	-50	-180	mA
			Outputs high			250		250		250	μΑ
ICC	$V_{CC} = 5.5 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$	$I_O = 0$,	Outputs low			30		30		30	mA
	v = vCC or GMD		Outputs disabled			250		250		250	μΑ
∆l _{CC} #	V _{CC} = 5.5 V, Other inputs at V _C	One input at 3.4	ΙV,			1.5		1.5		1.5	mA
C _i	V _I = 2.5 V or 0.5 \	/	Control inputs		7						pF
C _{io}	$V_0 = 2.5 \text{ V or } 0.5$	V	A or B ports		12						pF

^{*} On products compliant to MIL-STD-883, Class B, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		V _{CC} =	$V_{CC} = 5 \text{ V},$ $T_A = 25^{\circ}\text{C}$		SN54ABT646		SN74ABT646			
					MIN	MAX	MIN	MAX		
fclock	Clock frequency			125	0	125	0	125	MHz	
t _W	Pulse duration, CLK high or low				4	10,7	4		ns	
	Catura time A on B hatara Cl KABA an Cl KBAA	High	3.5		3.5	IIE.	3.5			
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑		3		3.	<i>'</i>	3		ns	
th	Hold time, A or B after CLKAB↑ or CLKBA↑				0		0		ns	

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]The parameters I_{OZH} and I_{OZI} include the input leakage current.

[§] This data sheet limit may vary among suppliers.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

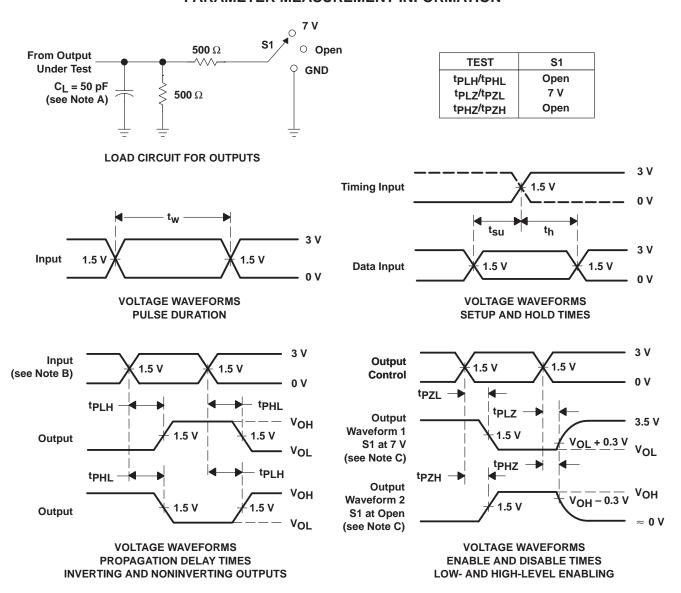
[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT646		SN74ABT646		UNIT	
	(INPOT)	(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
f _{max}			125					125		MHz	
^t PLH	CLKBA or CLKAB	A or B	2.2	4	6.8			2.2	7.8	ns	
^t PHL	CLNBA OF CLNAB	AOIB	1.7	4	7.4			1.7	8.4	115	
^t PLH	A or B	B or A	1.5	3	5.9		4	1.5	6.9	ns	
t _{PHL}		BOIA	1.5	3.3	5.9		14	1.5	6.9	113	
t _{PLH}	SAB or SBA†	B or A	1.5	4	6.1		2	1.5	7.1	ns	
t _{PHL}			1.5	3.6	6.9	1	Q	1.5	7.9		
^t PZH	ŌĒ	A or B	1	4.3	5.3	2		1	6.3	ns	
t _{PZL}	OE		2.1	5.8	7.4	30	,	2.1	8.8	113	
^t PHZ	ŌĒ	A or B	1.5	3.5	7.3	2		1.5	8.3	ns	
t _{PLZ}	OE	AOIB	1.5	3	7			1.5	7.5	113	
^t PZH	DIR	A or B	1.2	4.5	5.7			1.2	6.7	ns	
^t PZL	DIK		2.5	6.5	9			2.5	9.5	115	
^t PHZ	DID	DID	A or B	1.5	3.8	6.7			1.5	7.7	
t _{PLZ}	DIR A or B		1.5	3.8	7.2			1.5	8.2	ns	

[†] These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



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